



Enabling EUV Material Defectivity Qualification with Un-Patterned Wafer Inspection
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EUV adoption in logic and DRAM is closer to production than ever. Compared with 193i, EUV uses different materials, such as photo resist, and new material qualification is one of the key challenges. Ming will show how KLA-Tencor's advanced Surfscan unpattern inspection technology can help semiconductor fabs and material vendors to qualify new materials and reduce defectivity in production, with short time to results. With unique sensitivity enabled by revolutionary technology innovation, advanced Surfscan platform enabled materials quality differentiation, which otherwise showed no differentiation. For material vendors, this greatly helps to speed up material R&D; For semiconductor fabs, collaboration study showed correlation between unpatterned wafer inspection and inline product correlation, thus unpatterned wafer inspection provides a short time to results approach for material quality monitoring. Ming will share EUV material qualification examples from customer collaboration in this presentation.